

species "F" depicted in Figure 9 of the drawings. New claims 135-136 have been added. Claims 116-122, 135 and 136 read on species "F".

Applicants reserve the right to file at a later time a divisional application directed to the non-elected invention of Group II covered by claims 122-134.

The specification has been amended to correct a typographical error in the Japanese reference cited on page 7, line 4. The reference is cited correctly on page 6, line 6.

The "Brief Description of the Drawings" section on page 39 of the specification has been amended to add a description of drawing figures 16-22 which was missing from the application as filed. Support for this text is found in Figs. 16-22 as well as on pages 67 and 84 of the specification. No new matter has been added.

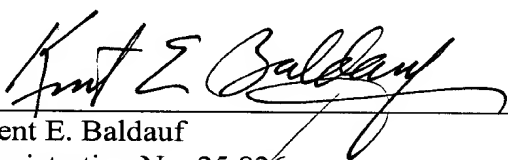
Pursuant to 37 C.F.R. §1.48(b), there is no change in inventorship as a result of this election.

The Examiner's favorable action is respectfully requested.

Respectfully submitted,

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MARKED-UP VERSION OF CHANGES MADE

IN THE TITLE:

[PRINTED WIRING BOARD-FORMING SHEET, VIA HOLE-FORMING METHOD, RESIN] SHEET [HAVING FILLED VIA HOLE,] FOR FORMING A PRINTED WIRING BOARD[, AND PROCESS FOR PRODUCING THE SAME]

IN THE SPECIFICATION:

The paragraph beginning at page 7, line 3, has been amended as follows:

In Japanese Patent Laid-Open Publication No. [81789/1988] 81789/1987, there is disclosed a process for producing a wiring board, which comprises punching a through hole into an uncalcined ceramic substrate (green sheet), then inserting a connecting pin in the through hole, printing a conductor layer on a surface of the substrate by screen printing, and calcining the green sheet.

The following new text has been added on page 39, between lines 11 and 12:

--Fig. 16 is a chart showing the steps of a conventional process for producing a double-sided metal TAB tape.

Fig. 17 is a schematic sectional view of a through hole of a printed wiring board according to the invention.

Fig. 18 is a schematic sectional view similar to that of Fig. 17 showing a through hole of a printed wiring board.

Fig. 19 is a view of a front surface of the double-sided metal TAB tape.

Fig. 20 is an enlarged view of a land and its vicinity on the front surface of the TAB tape.

Fig. 21 is a perspective view of a double-sided metal TAB tape from its back surface.

Fig. 22 is an enlarged view of a land and its vicinity on the back surface of the TAB tape.--

IN THE CLAIMS:

New claims 135 and 136 have been added as follows:

--135. The printed wiring board-forming sheet as claimed in claim 117, wherein the conductive metal chip is formed by punching at least one conductive metal sheet selected from the group consisting of a solder sheet, a solder plated metal sheet, a copper sheet and a copper alloy sheet.

136. The printed wiring board-forming sheet as claimed in claim 117, wherein the insulating resin sheet is made of at least one selected from the group consisting of polyimide, polyester, polypropylene, polyphenylene sulfide, polyvinylidene chloride, Eval, glass epoxy and a BT resin.--